

12A, 200V, 0.500 Ohm, P-Channel Power MOSFET

This P-Channel enhancement mode silicon gate power field effect transistor is an advanced power MOSFET designed, tested, and guaranteed to withstand a specified level of energy in the breakdown avalanche mode of operation. All of these power MOSFETs are designed for applications such as switching regulators, switching convertors, motor drivers, relay drivers, and drivers for high power bipolar switching transistors requiring high speed and low gate drive power. These types can be operated directly from integrated circuits.

Formerly developmental type TA17522.

Ordering Information

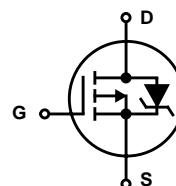
PART NUMBER	PACKAGE	BRAND
IRFP9240	TO-247	IRFP9240

NOTE: When ordering, use the entire part number.

Features

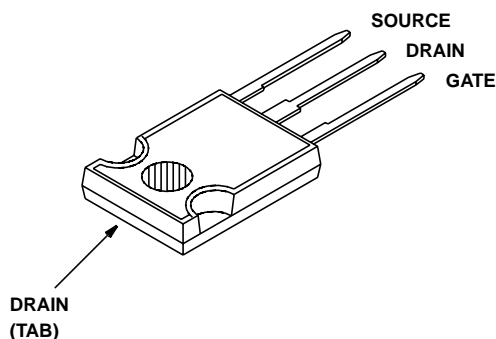
- 12A, 200V
- $r_{DS(ON)} = 0.500\Omega$
- Single Pulse Avalanche Energy Rated
- SOA is Power Dissipation Limited
- Nanosecond Switching Speeds
- Linear Transfer Characteristics
- High Input Impedance

Symbol



Packaging

JEDEC STYLE TO-247



Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, Unless Otherwise Specified

	IRFP9240	UNITS
Drain to Source Breakdown Voltage (Note 1)	-200	V
Drain to Gate Voltage ($R_{GS} = 20\text{k}\Omega$) (Note 1)	-200	V
Continuous Drain Current	-12	A
$T_C = 125^\circ\text{C}$	-7.5	A
Pulsed Drain Current (Note 3)	-48	A
Gate to Source Voltage	± 20	V
Maximum Power Dissipation	150	W
Linear Derating Factor	1.2	W/ $^\circ\text{C}$
Single Pulse Avalanche Energy Rating (Note 4)	790	mJ
Operating and Storage Temperature	-55 to 150	$^\circ\text{C}$
Maximum Temperature for Soldering		
Leads at 0.063in (1.6mm) from Case for 10s.	300	$^\circ\text{C}$
Package Body for 10s, See Techbrief 334	260	$^\circ\text{C}$

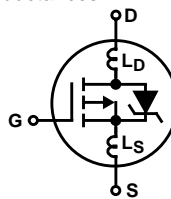
CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. $T_J = 25^\circ\text{C}$ to 125°C .

Electrical Specifications $T_C = 25^\circ\text{C}$, Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Drain to Source Breakdown Voltage	BV_{DSS}	$I_D = -250\mu\text{A}$, $V_{GS} = 0\text{V}$ (Figure 10)	-200	-	-	V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}$, $I_D = -250\mu\text{A}$	-2.0	-	-4.0	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = \text{Rated } BV_{DSS}$, $V_{GS} = 0\text{V}$	-	-	25	μA
		$V_{DS} = 0.8 \times \text{Rated } BV_{DSS}$, $V_{GS} = 0\text{V}$, $T_J = 125^\circ\text{C}$	-	-	250	μA
On-State Drain Current (Note 2)	$I_{D(ON)}$	$V_{DS} > I_{D(ON)} \times r_{DS(ON)MAX}$, $V_{GS} = -10\text{V}$	-12	-	-	A
Gate to Source Leakage Current	I_{GSS}	$V_{GS} = \pm 20\text{V}$	-	-	± 100	nA
Drain to Source On Resistance (Note 2)	$r_{DS(ON)}$	$I_D = -6.3\text{A}$, $V_{GS} = -10\text{V}$ (Figures 8, 9)	-	0.380	0.500	Ω
Forward Transconductance (Note 2)	g_{fs}	$V_{DS} \leq -50\text{V}$, $I_D = -6.3\text{A}$ (Figure 12)	3.8	5.7	-	S
Turn-On Delay Time	$t_{d(ON)}$	$V_{DD} = -100\text{V}$, $I_D \approx -12\text{A}$, $R_G = 9.1\Omega$, $V_{GS} = -10\text{V}$, $R_L = 7.6\Omega$, (Figures 17, 18) MOSFET Switching Times are Essentially Independent of Operating Temperature	-	18	22	ns
Rise Time	t_r		-	45	68	ns
Turn-Off Delay Time	$t_{d(OFF)}$		-	75	90	ns
Fall Time	t_f		-	29	44	ns
Total Gate Charge (Gate to Source + Gate to Drain)	$Q_{g(TOT)}$	$V_{GS} = -10\text{V}$, $I_D = -12\text{A}$, $V_{DS} = 0.8 \times \text{Rated } BV_{DSS}$ $I_{g(REF)} = -1.5\text{mA}$ (Figures 14, 19, 20)	-	38	57	nC
Gate to Source Charge	Q_{gs}	Gate Charge is Essentially Independent of Operating Temperature	-	8	-	nC
Gate to Drain "Miller" Charge	Q_{gd}		-	21	-	nC
Input Capacitance	C_{ISS}	$V_{DS} = -25\text{V}$, $V_{GS} = 0\text{V}$, $f = 1\text{MHz}$ (Figure 11)	-	1400	-	pF
Output Capacitance	C_{OSS}		-	350	-	pF
Reverse Transfer Capacitance	C_{RSS}		-	140	-	pF
Internal Drain Inductance	L_D	Measured From the Contact Screw on Header Closer to Source and Gate Pins to Center of Die	-	5.0	-	nH
Internal Source Inductance	L_S	Measured From the Source Pin, 6mm (0.25in) From Header to Source Bonding Pad	-	12.5	-	nH
Thermal Resistance Junction to Case	$R_{\theta JC}$		-	-	0.83	$^\circ\text{C/W}$
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	Free Air Operation	-	-	30	$^\circ\text{C/W}$



Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Continuous Source to Drain Current	I_{SD}	Modified MOSFET Symbol Showing the Integral Re- verse P-N Junction Rectifier	-	-	-12	A
Pulse Source to Drain Current (Note 3)	I_{SDM}		-	-	-48	A
Source to Drain Diode Voltage (Note 2)	V_{SD}	$T_J = 25^\circ\text{C}$, $I_{SD} = -12\text{A}$, $V_{GS} = 0\text{V}$, (Figure 13)	-	-	-1.5	V
Reverse Recovery Time	t_{rr}	$T_J = 25^\circ\text{C}$, $I_{SD} = -11\text{A}$, $dI_{SD}/dt = 100\text{A}/\mu\text{s}$	-	210	-	ns
Reverse Recovery Charge	Q_{RR}	$T_J = 25^\circ\text{C}$, $I_{SD} = -11\text{A}$, $dI_{SD}/dt = 100\text{A}/\mu\text{s}$	-	2.0	-	μC

NOTES:

- Pulse test: pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- Repetitive rating: pulse width limited by maximum junction temperature. See Transient Thermal Impedance curve (Figure 3).
- $V_{DD} = 50\text{V}$, starting $T_J = 25^\circ\text{C}$, $L = 8.2\text{mH}$, $R_G = 50\Omega$, peak $I_{AS} = 12\text{A}$ (Figures 15, 16).

Typical Performance Curves Unless Otherwise Specified

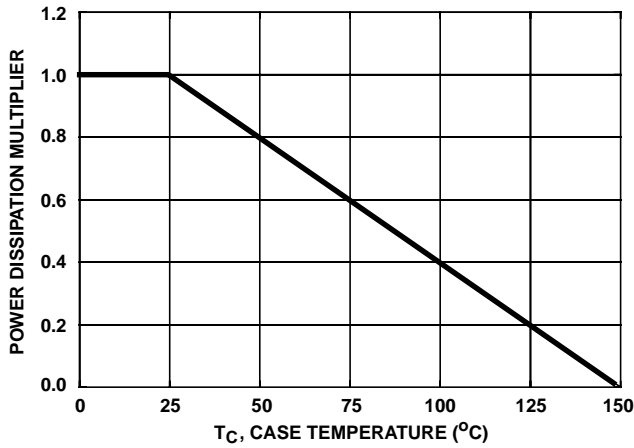


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

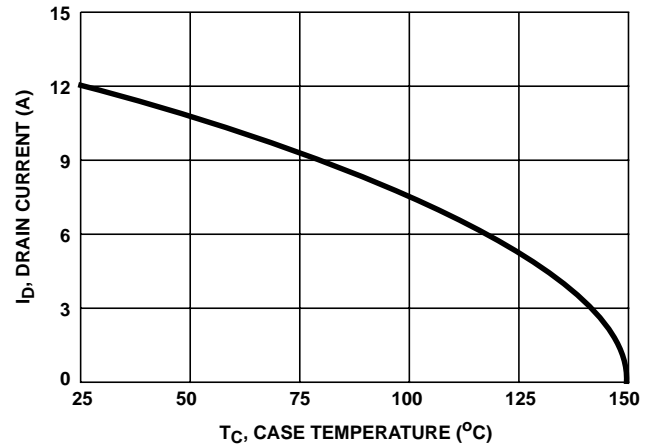


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

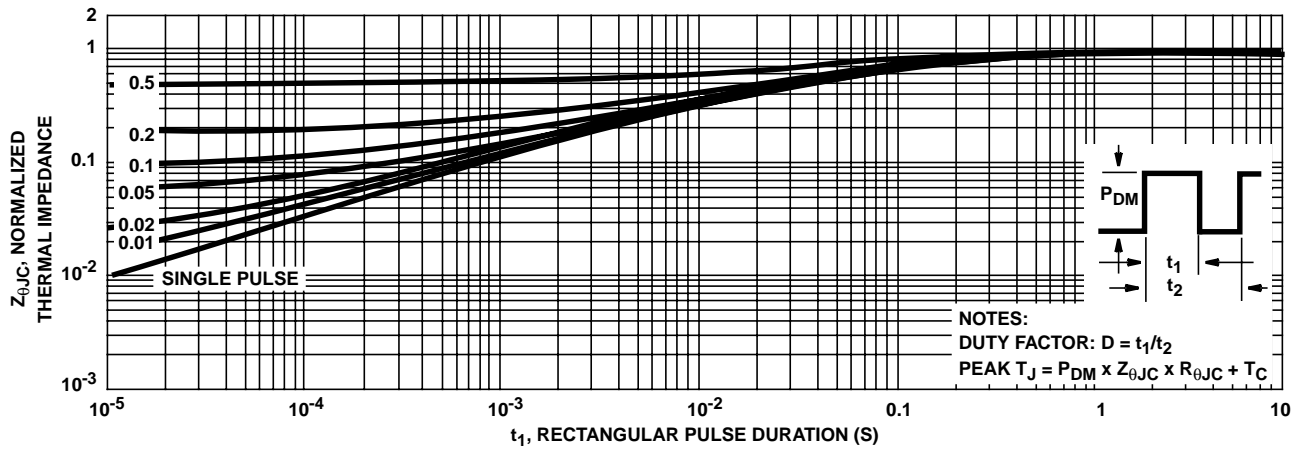


FIGURE 3. MAXIMUM TRANSIENT THERMAL IMPEDANCE

Typical Performance Curves Unless Otherwise Specified (Continued)

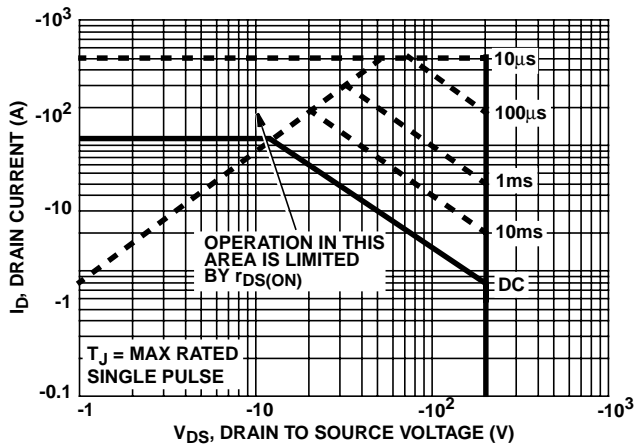


FIGURE 4. FORWARD BIAS SAFE OPERATING AREA

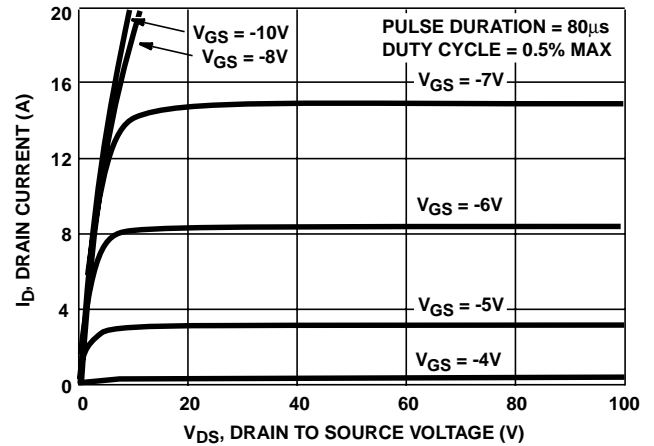


FIGURE 5. OUTPUT CHARACTERISTICS

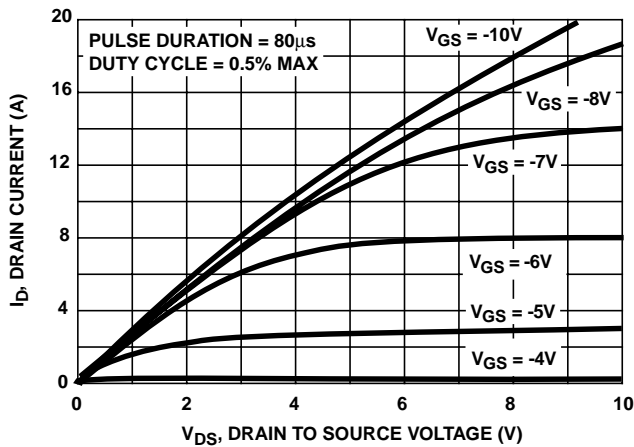


FIGURE 6. SATURATION CHARACTERISTICS

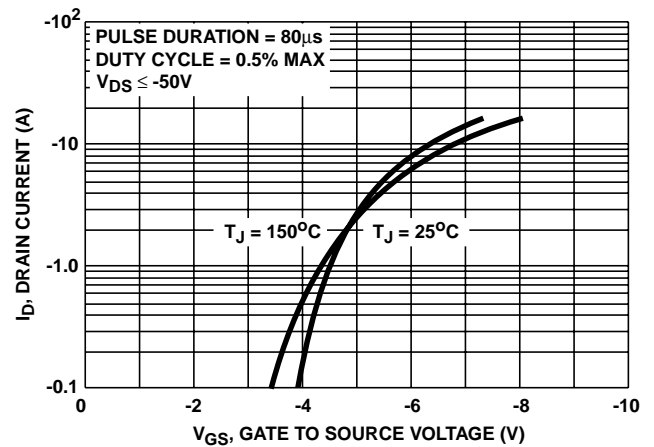
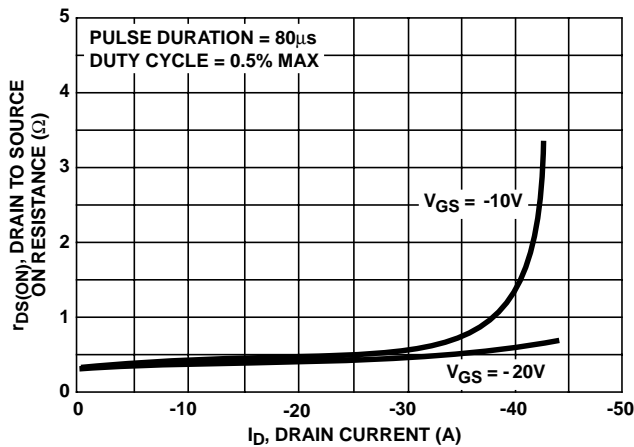


FIGURE 7. TRANSFER CHARACTERISTICS



NOTE: Heating effect of 2μs pulse is minimal.

FIGURE 8. DRAIN TO SOURCE ON RESISTANCE vs GATE VOLTAGE AND DRAIN CURRENT

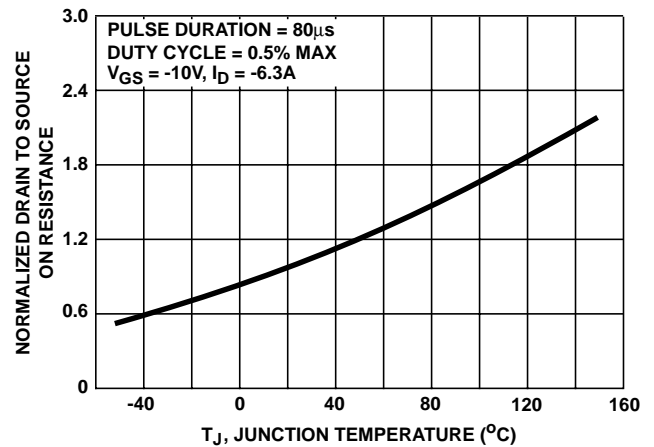


FIGURE 9. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE

Typical Performance Curves Unless Otherwise Specified (Continued)

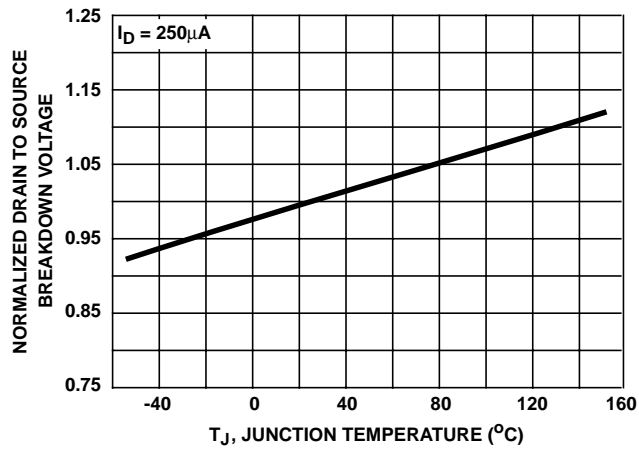


FIGURE 10. NORMALIZED DRAIN TO SOURCE BREAKDOWN VOLTAGE vs JUNCTION TEMPERATURE

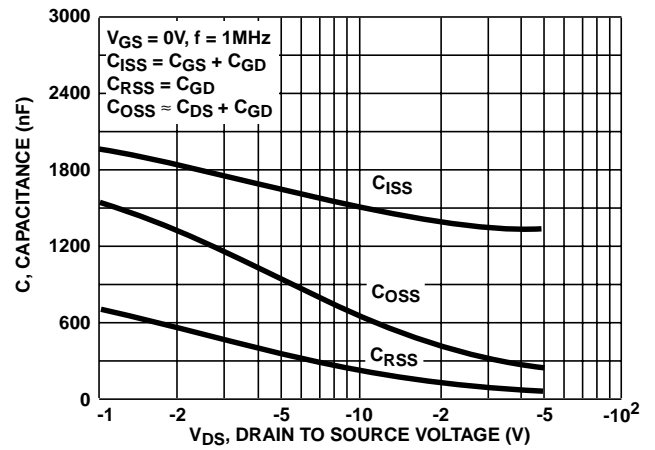


FIGURE 11. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE

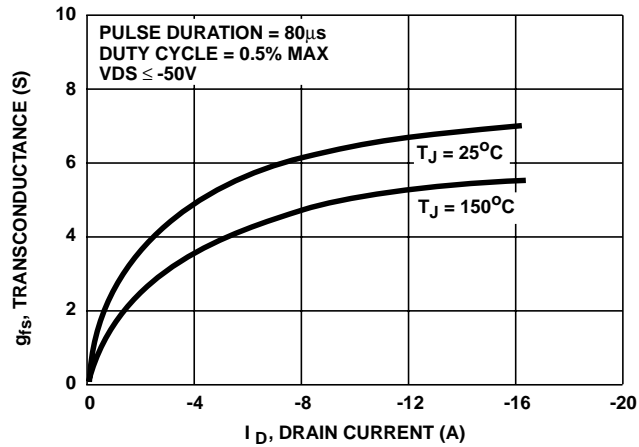


FIGURE 12. TRANSCONDUCTANCE vs DRAIN CURRENT

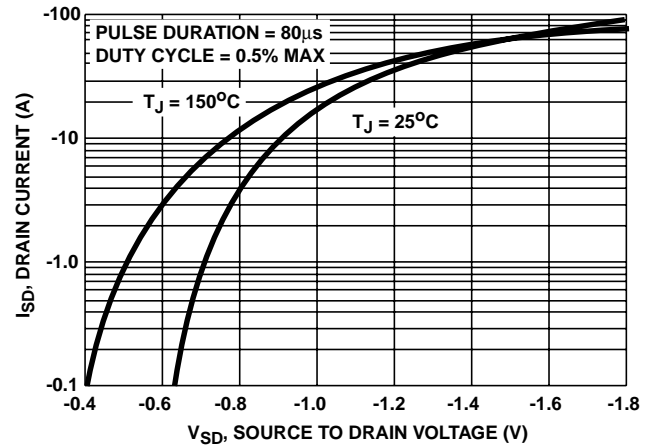


FIGURE 13. SOURCE TO DRAIN DIODE VOLTAGE

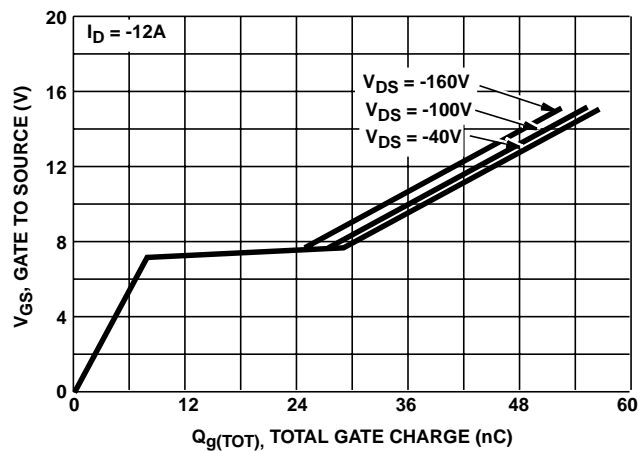


FIGURE 14. GATE TO SOURCE VOLTAGE vs GATE CHARGE

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Sales Office Headquarters

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Intersil Corporation
P. O. Box 883, Mail Stop 53-204
Melbourne, FL 32902
TEL: (407) 724-7000
FAX: (407) 724-7240

EUROPE

Intersil SA
Mercure Center
100, Rue de la Fusee
1130 Brussels, Belgium
TEL: (32) 2.724.2111
FAX: (32) 2.724.22.05

ASIA

Intersil (Taiwan) Ltd.
7F-6, No. 101 Fu Hsing North Road
Taipei, Taiwan
Republic of China
TEL: (886) 2 2716 9310
FAX: (886) 2 2715 3029